

PACKAGE MATERIAL DECLARATION DATASHEET

Cypress Package Code	LZ	Body Size (mil/mm)	5 x 7 mm
Package Weight – Site 1	181.7002 mg	Package Weight – Site 2	N/A

SUMMARY

The 6L – CLCC Pb-free package is compliant to RoHS. Cypress Ordering Part Numbers containing an “X” (e.g. CY7C1328G-133AXI, CY2308SXC-1HT) meet the Directive 2002/95/EC (RoHS) requirement.

**ASSEMBLY Site 1: ECERA Taiwan (ER)
Package Qualification Report # 131805 (Note 1)**

I. DECLARATION OF PACKAGED UNITS

A. BANNED SUBSTANCES

Materials from Level A of the EIA/JIG/JGPSSI/EICTA Material Composition Declaration Guide and EU RoHS. Listed in the table below are materials that are neither contained nor intentionally added to this product.

Substances / Compounds	Weight by mg	PPM	Analysis Report (Note 2)
Cadmium and Cadmium Compounds	0	< 5.0	COA-LZ6L-ER
Hexavalent Chromium and its Compounds	0	< 5.0	
Lead and Lead Compounds	0	< 5.0	
Mercury and Mercury Compounds	0	< 5.0	
Polybrominated Biphenyls (PBB)	0	< 5.0	
Polybrominated Diphenylethers (PBDE)	0	< 5.0	
Asbestos	0	0	As per MSDS
Azo colorants	0	0	As per MSDS
Ozone Depleting Substances	0	0	As per MSDS
Polychlorinated Biphenyls (PCBs)	0	0	As per MSDS
Polychlorinated Naphthalenes	0	0	As per MSDS
Radioactive Substances	0	0	As per MSDS
Shortchain Chlorinated Paraffins	0	0	As per MSDS
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	0	0	As per MSDS
Tributyl Tin Oxide (TBTO)	0	0	As per MSDS
Formaldehyde	0	0	As per MSDS

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.

Note 2: Report available from Cypress Sales Offices or Distributors.

Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered “non-existent in the product”. In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information

Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data

B. MATERIAL COMPOSITION (Note 3)

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogenous material	PPM	% weight of substance per package
Ceramic	Base Package	Al ₂ O ₃	1344-28-1	71.6873	90.0000%	394,537	39.4537%
		SiO ₂	14808-60-7	4.7792	6.0000%	26,302	2.6302%
		Cr ₂ O ₃	1308-38-9	1.5931	2.0000%	8,767	0.8767%
		Mo	7439-98-7	1.5931	2.0000%	8,767	0.8767%
Fe/Co/Ni Alloy	Base Package	Fe	7439-89-6	23.7515	45.0000%	130,718	13.0718%
		Ni	7440-02-0	13.1953	25.0000%	72,621	7.2621%
		Co	7440-48-4	7.9172	15.0000%	43,573	4.3573%
		Ag	7440-22-4	5.8059	11.0000%	31,953	3.1953%
		Cu	7440-50-8	2.1112	4.0000%	11,619	1.1619%
Plate	Base Package	W	7440-33-7	2.9865	75.0000%	16,436	1.6436%
		Ni	7440-02-0	0.8760	22.0000%	4,821	0.4821%
		Au	7440-57-5	0.1195	3.0000%	657	0.0657%
Fe/Co/Ni Alloy	Lid	Fe	7439-89-6	9.0664	53.0000%	49,897	4.9897%
		Ni	7440-02-0	5.3030	31.0000%	29,185	2.9185%
		Co	7440-48-4	2.7370	16.0000%	15,063	1.5063%
Quartz Crystal	Oscillator	SiO ₂	14808-60-7	0.8678	100.0000%	4,776	0.4776%
Silver Electrode	Electrode	Ag	7440-22-4	0.0260	100.0000%	143	0.0143%
IC Die	Circuit	Si	7440-21-3	27.2830	100.0000%	150,154	15.0154%
Die Attach	Adhesive	Ag Powder	7440-22-4	0.0004	74.0741%	2	0.0002%
		Petroleum Solvent	Trade Secret	0.0000	7.4074%	0	0.0000%
		Si Resin, Other	Trade Secret	0.0001	18.5185%	1	0.0001%
Wire	Interconnect	Au	7440-57-5	0.0007	100.0000%	4	0.0004%

Package Weight (mg): 181.7002

% Total: 100.0000

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Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data

II. DECLARATION OF PACKAGING INDIRECT MATERIALS

Type	Material	Lead PPM	Cadmium PPM	Cr VI PPM	Mercury PPM	PBB PPM	PBDE PPM	Analysis Report (Note2)
Tape & Reel	Cover tape	< 2.0	< 2.0	< 2.0	< 2.0	< 5.0	< 5.0	CoA-COVT-R
	Carrier tape	< 2.0	< 2.0	< 2.0	< 2.0	< 5.0	< 5.0	CoA-CART-R
	Plastic Reel	< 2.0	< 2.0	< 2.0	< 2.0	< 5.0	< 5.0	CoA-PLRL-R
Others	Shielding bag	< 2.0	< 2.0	< 2.0	< 2.0	< 5.0	< 5.0	CoA-SBAG-R
	Protective Band	< 2.0	< 2.0	< 2.0	< 2.0	< 5.0	< 5.0	CoA-PROB-R
	Shipping and Inner Box	< 10.0	< 4.0	< 4.0	< 5.0	-----	-----	CoA-ABOX-R
	Bubble Pack	< 2.0	< 2.0	< 2.0	< 2.0	< 100.0	< 90.0	CoA-BUBP-R

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Document History Page

Document Title: 6L-CLCC (5X7X1.8MM) PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET

Document Number: 001-88952

Rev.	ECN No.	Orig. of Change	Description of Change
**	4106744	CMG	New Release
*A	5508003	HLR	Changed Cypress Logo. Changed the substances with Proprietary to "Trade Secret".
		DCON	Removed distribution and posting from the document history page.

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